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# UNITED STATES PATENT AND TRADEMARK OFFICE

UNITED STATES DEPARTMENT OF COMMERCE United States Patent and Trademark Office Address: COMMISSIONER OF PATENTS AND TRADEMARKS P.O. BOX 1450 Alexandria, Virginia 22313-1450

APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/044,799	01/10/2002	Jun Seo	8750-018 8382		
7.	590 05/09/2003				
MARGER JOHNSON & McCOLLOM, P.C. 1030 SW Morrison Street Portland, OR 97205			EXAMINER		
			LEE, GRANVILL D		
			ART UNIT	PAPER NUMBER	
			2825		

DATE MAILED: 05/09/2003

Please find below and/or attached an Office communication concerning this application or proceeding.

					/				
Š		Application No.		Applicant(s)	/				
4		10/044,799		SEO ET AL.					
4	Office Action Summary	Examiner		Art Unit					
		Granvill D Lee, Jr		2825					
Period fo	The MAILING DATE of this communication apport	pears on the cover	sheet with the co	orrespondence addre	?SS				
A SH THE   - External after - If the - If NO - Failu - Any I	ORTENED STATUTORY PERIOD FOR REPL MAILING DATE OF THIS COMMUNICATION. nsions of time may be available under the provisions of 37 CFR 1.1 SIX (6) MONTHS from the mailing date of this communication. It period for reply specified above is less than thirty (30) days, a reply or period for reply is specified above, the maximum statutory period are to reply within the set or extended period for reply will, by statute reply received by the Office later than three months after the mailing and patent term adjustment. See 37 CFR 1.704(b).	136(a). In no event, howe ly within the statutory mini will apply and will expire S e, cause the application to	wer, may a reply be tim mum of thirty (30) days SIX (6) MONTHS from to become ABANDONED	ely filed will be considered timely. the mailing date of this comm (35 U.S.C. § 133).	nunication.				
1)⊠	Responsive to communication(s) filed on 10.	January 2002 .							
2a) <u></u> □	This action is <b>FINAL</b> . 2b)⊠ Th	nis action is non-fir	nal.						
3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.									
•	ion of Claims								
4) 🖂	Claim(s) <u>1-14</u> is/are pending in the application								
	4a) Of the above claim(s) is/are withdrawn from consideration.								
5)	5) Claim(s) is/are allowed.								
.6)⊠	_6)⊠ Claim(s) <u>1-3 and 5-14</u> is/are rejected.								
,	)⊠ Claim(s) <u>4</u> is/are objected to.								
· ·	Claim(s) are subject to restriction and/o	or election requirer	ment.						
	ion Papers	or.							
•	The specification is objected to by the Examine The drawing(s) filed on is/are: a)□ acce		ed to by the Evar	miner					
10)									
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).  11) The proposed drawing correction filed on is: a) approved b) disapproved by the Examiner.									
/	If approved, corrected drawings are required in re			•					
12) The oath or declaration is objected to by the Examiner.									
Priority	under 35 U.S.C. §§ 119 and 120								
-	Acknowledgment is made of a claim for foreig	n priority under 35	5 U.S.C. § 119(a	)-(d) or (f).					
•	⊠ All b) Some * c) None of:								
·	1. Certified copies of the priority documents have been received.								
	2. Certified copies of the priority documents have been received in Application No								
* ;	3. Copies of the certified copies of the price application from the International Buse the attached detailed Office action for a list	ureau (PCT Rule 1	l7.2(a)).		age				
14) Acknowledgment is made of a claim for domestic priority under 35 U.S.C. § 119(e) (to a provisional application).									
	a)  The translation of the foreign language pr Acknowledgment is made of a claim for domes	ovisional applicati	on has been rec	eived.					
Attachmer		and priority under o	2 3.3.3. 33 120						
1) Notice	ce of References Cited (PTO-892) ce of Draftsperson's Patent Drawing Review (PTO-948) rmation Disclosure Statement(s) (PTO-1449) Paper No(s)	4) 5) 6)	Notice of Informal I	/ (PTO-413) Paper No(s). Patent Application (PTO-					

17.

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#### DETAILED ACTION

### Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims 1 and 5-9 are rejected under 35 U.S.C. 103(a) as being unpatentable over Lee et al. (US Pat. 6,355,547) in view Doan (US Pat. 6,303, 958).

In view of these claims (esp. clm. 1), Lee et al. makes a self-aligned contact (SAC) for a device by forming a gate stack (Fig. 5a #208) on a semiconductor substrate, a conformal dielectric layer (#209) over the gate stack, applying an etch-stop material layer (#210) over the conformal dielectric layer, and then eventually etching back the conformal dielectric layer to form a gate spacer (Fig. 9). However, Lee et al. fails to remove the upper portion of the etch-stop material to expose the conformal dielectric layer and then etching the conformal dielectric layer.

Doan et al. in a process of making a capacitor device, shows the removal of a portion of the etch-stop material (Fig. 7 #120 & 121) to have remaining the exposed portion of the dielectric layer, which it too is etched away (Fig. 8). Therefore, it would have been obvious to a person of ordinary skill in the

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art at the time of the invention to modify Lee et al. with that of Doan in order to achieve a better etch result having selected materials that now lend themselves to preferred fluorine etches (like CF4, CHF3, and HBr) (Col. 7 line 55-Col. 8 line 10).

In view of claims 5-6, Lee et al. uses a organic photoresist material (Fig. 5a #210) to form an etch-stop.

In continued view of claim 7, Doan uses a mixture of fluorine etch, like CF4 or CHF3 and HBr (Col. 8 lines 1-9).

In view of claim 8, Lee et al. uses the selectivity of the upper photoresist layer (#220) to etch the dielectric layer.

In view of claim 9, Lee et al. uses a thickness of 3500-5000 angstroms for the layer #212 and #240.

Claims 2-3 and 10-14 are rejected under 35 U.S.C. 103(a) as being unpatentable over Lee et al. (US Pat. 6,355,547) in view Doan (US Pat. 6,303, 958) in further view of Hsieh et al. (US Pat Pub. 2001/0015455).

In view of these claims (esp. clm. 10), Lee et al. makes a self-aligned contact (SAC) for a device by forming a gate stack (Fig. 5a #208) on a semiconductor substrate, a conformal dielectric layer (#209) over the gate stack, applying an etch-stop material layer (#210) over the conformal dielectric layer, and then eventually etching back the conformal dielectric layer to form a

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gate spacer (Fig. 9). Doan et al. in a process of making a capacitor device, shows the removal of a portion of the etch-stop material (Fig. 7 #120 & 121) to have remaining the exposed portion of the dielectric layer, which it too is etched away. However, both inventors fail to use a spacer that is lower than the hard mask. Hsieh et al. uses a hard mask (Fig. 1 #22) substantially above the spacer (sp).

Therefore, it would have been obvious to a person of ordinary skill in the art at the time of the invention to modify Lee et al. and Doan with that of Hsieh et al. for control purposes. Whereas, normally utilized spacers act to both protect the gate against etching and for doping purposes, lower spacers now need not protect the gate if a hard mask is used (as by Hsieh et al.), but now act to control the doping of the electrodes (para. 0038).

In view of claim 2, Hsieh et al. creates a gate stack using gate oxide which is patterned (Fig. 1 #14), an electrode (#90-#93) and a hard mask (#22).

In continuing view of claim 3, Hsieh et al. uses a gate spacer lower than the hard mask.

In view of claim 13, Lee et al. forms a SAC hole adjacent to the gate stacks (Fig. 7a).

In view of claim 14, Lee et al. deposits a conductive layer within the hole and then planarizing the layer to form a contact pad (Abstr.).

## Allowable Subject Matter

Claim 4 is objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.

## **Contact Information**

Any inquiry concerning this communication or earlier communications for the examiner should be directed to Granvill Lee whose telephone number is (703) 306-5865. The examiner can be normally reached on Monday thru Thursday from 7:00 am to 5:30 pm.

If attempts to reach the examiner by telephone are not successful, the examiner's supervisor, Matthew Smith can be reached on (703) 308-1323. The fax phone number for this group is (703) 308-7722.

Any inquiry of a general nature relating to status or otherwise should be directed to the receptionist whose telephone number is 703-308-1782.

Examiner Granvill Lee Art Unit 2825

Gl

4/18/03

MATTHEW SMITH
SUPERVISORY PATENT EXAMINER

Ma Ol Sel

TECHNOLOGY CENTER 2800